

Antenna

YC0009AA Datasheet

Antenna Services

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About the Document

Revision History

Version	Date	Author	Note
-	2020-09-20	Kenny YIN	Creation of the document
1.0	2020-09-20	Kenny YIN	First official release
1.1	2021-01-12	Kenny YIN	Updated the antenna image in Chapter 2.

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1 Product Description

The antenna is designed for superior performance, and can be widely used for wireless applications.

We provide comprehensive antenna design support such as simulation, testing and manufacturing for custom antenna solutions to meet your specific application needs.

2 Product Features

- Wi-Fi/BT
- High efficiency
- Excellent performance



3 Product Specifications

Passive Electrical Specifications

Frequency Range	2400–2500 MHz
Input Impedence	50 Ω
Return Loss	≤ 2.0
Gain	≤ 4 dBi
Polarization Type	Linear

Mechanical Specifications

Antenna Size	3.2 mm $\times$ 1.6 mm $\times$ 0.5 mm
Casing	-
Radiator	Ceramic patch
Connector Type	SMD
Working Temperature	-40 °C to +85 °C
Radome Color	-

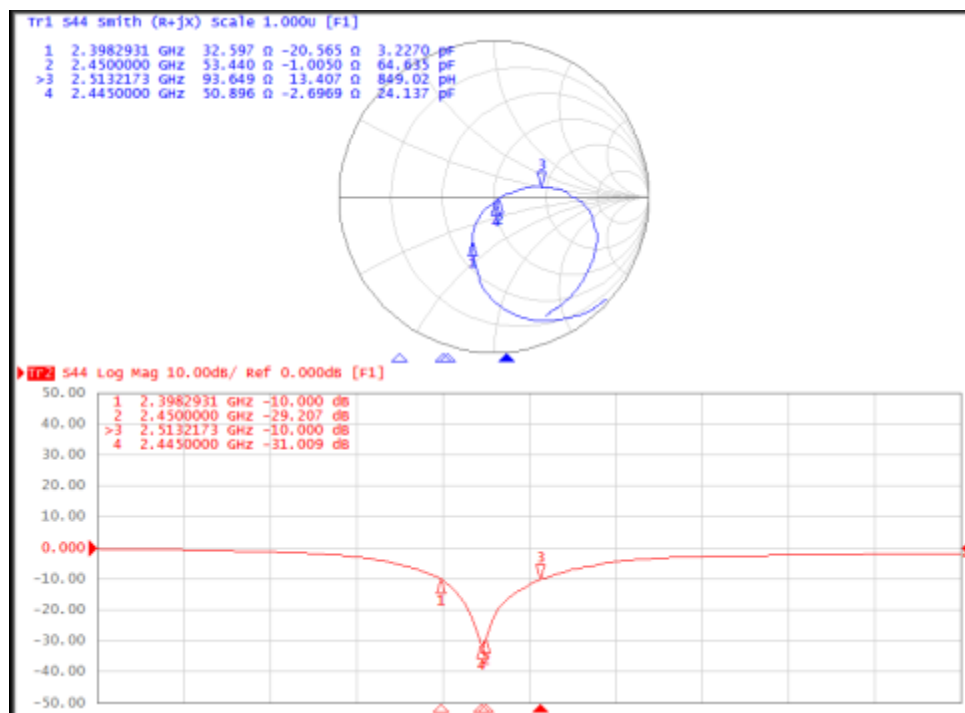
4 Overall Performance

4.1. Test Environment

- KEYSIGHT VNA Network Analyzer E5063A, 100 kHz – 6.5 GHz
- RayZone® 2800 Chamber 5G (FR1) SISO/MIMO, 400 MHz – 6.0 GHz



4.2. Return Loss



Frequency (MHz)	2390	2450	2513
Return Loss	-10	-29.2	-10

4.3. Efficiency

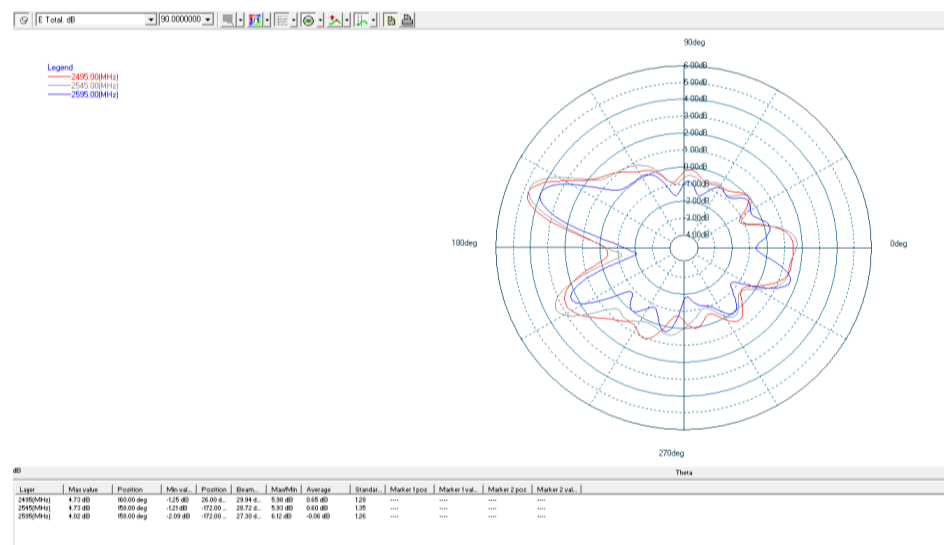
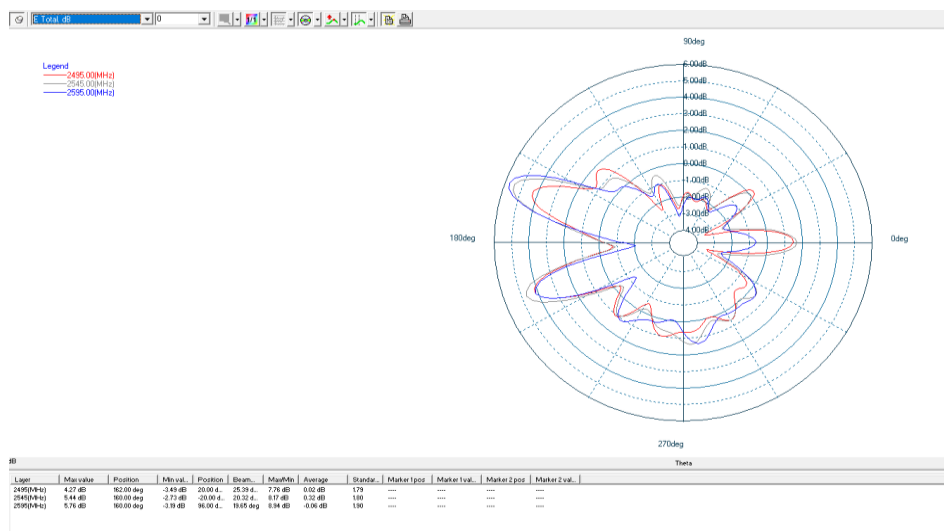
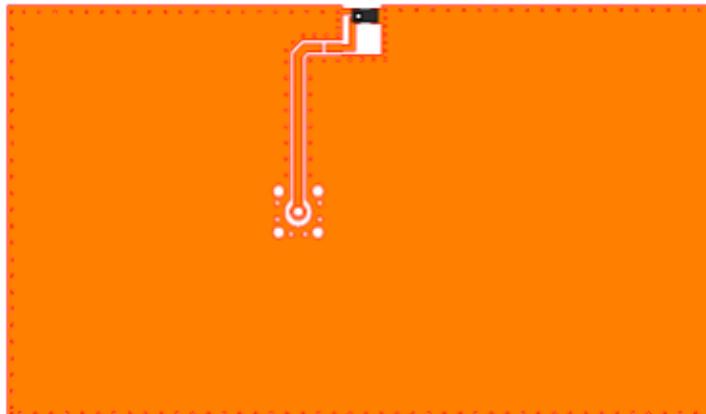
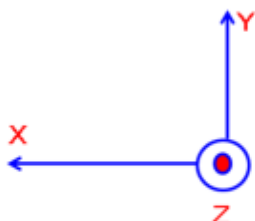
Frequency (MHz)	2400	2450	2500
Efficiency (%)	72.1	78.2	71.8

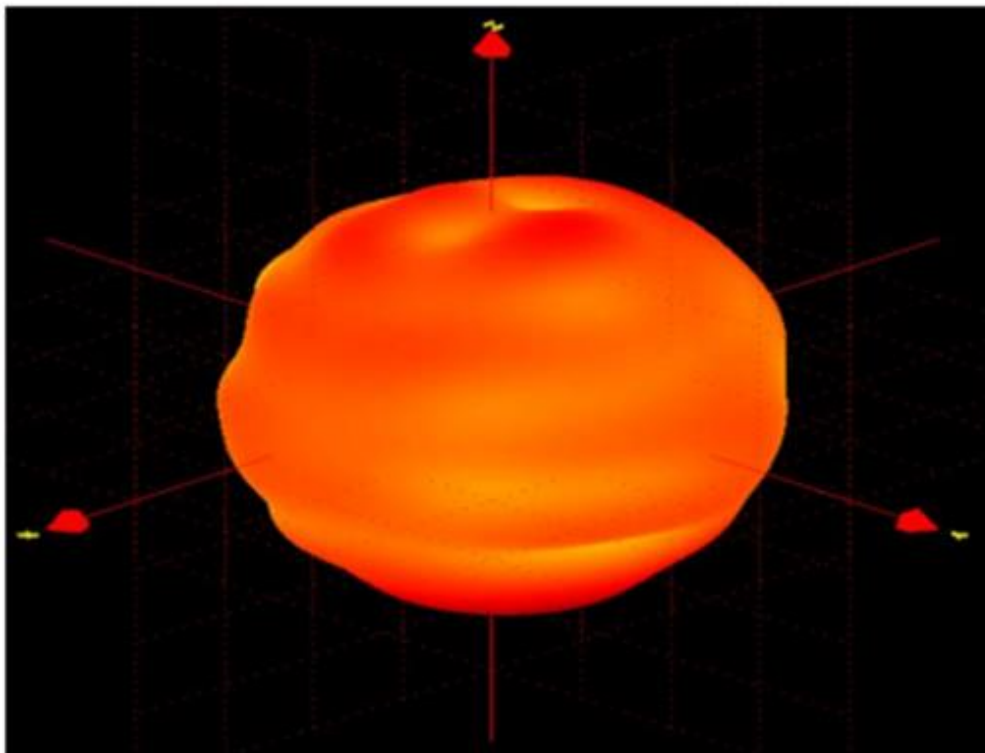
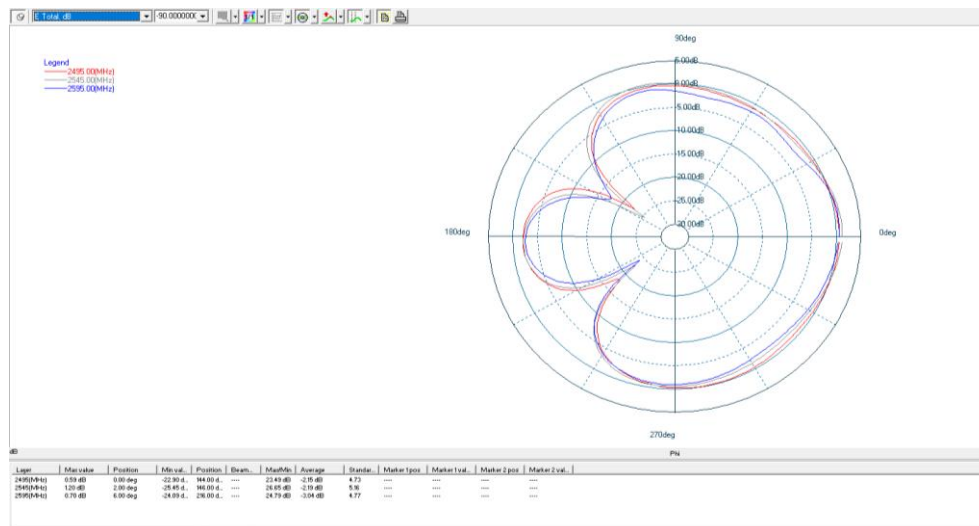
4.4. Gain

Frequency (MHz)	2400	2450	2500
Gain	1.76	4.08	2.53

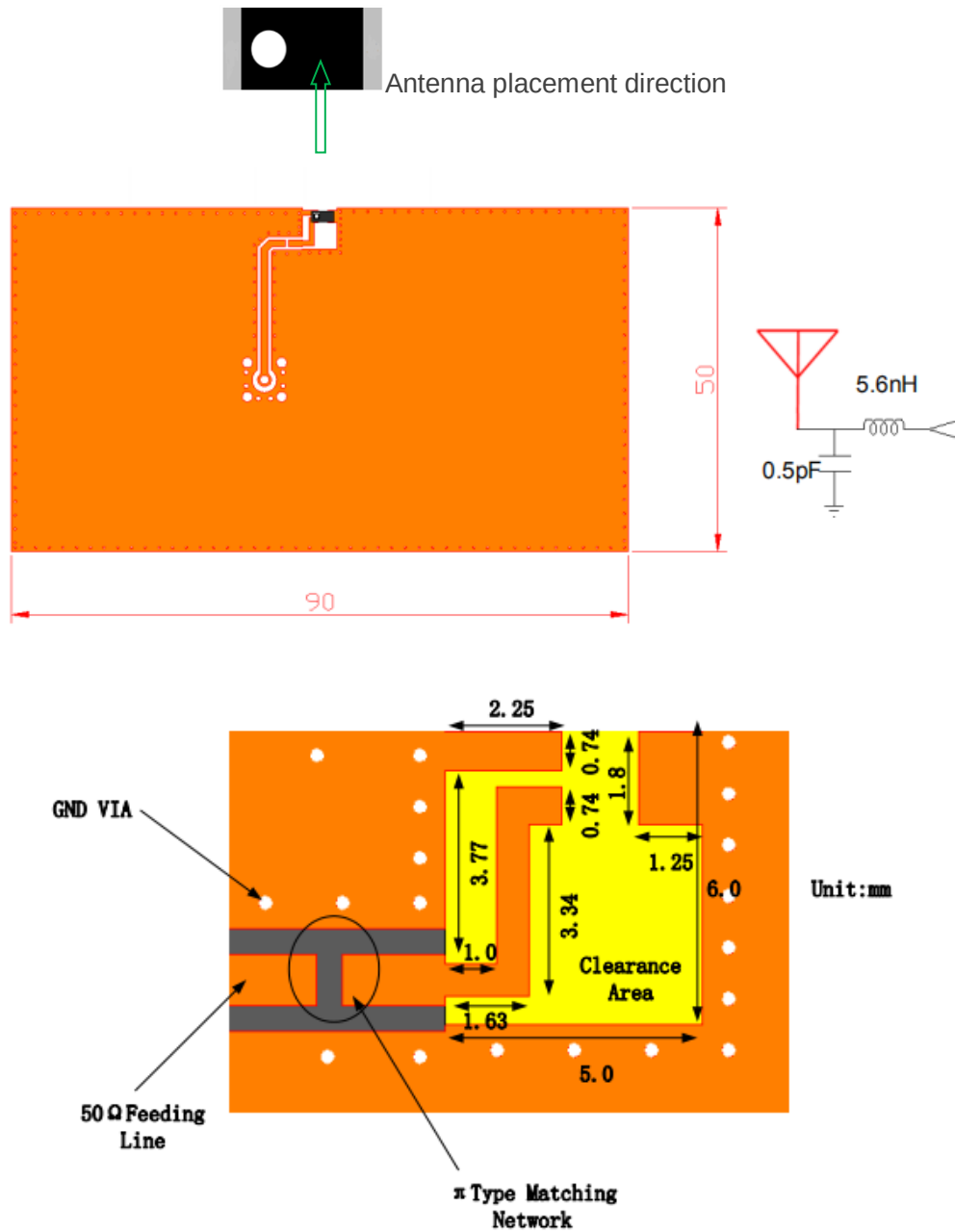
4.5. Radiation Patterns

coordinates:

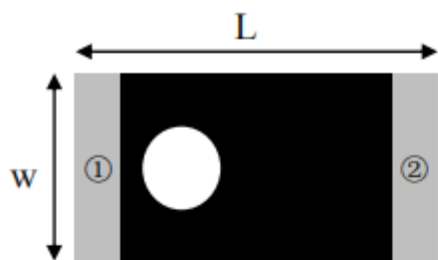




4.6. Reference PCB Design (Unit: mm)

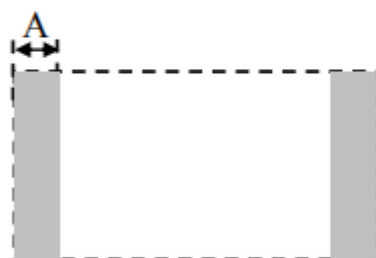


5 Product Size



(Top View)

Number	Terminal Name
①	INPUT
②	NC



(Bottom View)



(Side View)

Symbols	L	W	T	A
Dimensions	3.2+/-0.2	1.6+/-0.2	0.5+/-0.1	0.4+/-0.1

6 Reliability Test

Temperature Range	25 ±5 °C
Relative Humidity Range	55–75 %
Operating Temperature Range	-40 °C to +85 °C
Storage Temperature Range	-40 °C to +85 °C

6.1. Vibration Resist

The device should fulfil the electrical specification after being applied to the vibration of 10–55 Hz with amplitude of 1.5 mm for 2 hours in X, Y and Z directions respectively.

6.2. Drop Shock

The device should have no mechanical damage after dropping onto the hard wooden board from the height of 100 cm for 3 times at each facet of the 3 dimensions of the device.

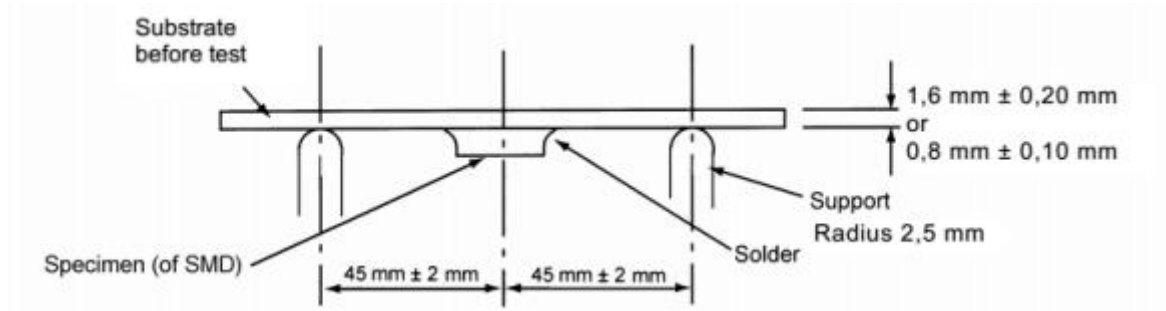
6.3. Resistance to Soldering Heat

The device should have no damage after pre-heating at 120–150 °C for 120 seconds and immersion in solder Sn at 255 °C ±10 °C for 5 ±0.5 seconds, or electric iron at 300 °C ±10 °C for 3 ±0.5 seconds.

6.4. Adhesive Strength of Termination

The device have no remarkable damage or removal of the termination after horizontal force of 5 N ($\leq$ 0603); 10 N ($>$ 0603) for 10 ±1 seconds.

6.5. Bending Resist Test



Weld the product to the central part of the PCB with the thickness 1.6 ± 0.2 mm or 0.8 ± 0.1 mm as the illustration shows, and keep exerting force arrow-ward on it at speed of 1 mm/s, and hold for 5 ± 1 s at the position of 1.5 mm bending distance, so far, any peeling-off of the product metal coating should not be detected.

6.6. Moisture Proof

The device should fulfil the electrical specification after being exposed to the temperature 60 ± 2 °C and the relative humidity 90–95 % for 96 hours and 1–2 hours recovery time under normal condition.

6.7. High Temperature Endurance

The device should fulfil the electrical specification after being exposed to temperature 85 ± 5 °C for 96 ± 2 hours and 1–2 hours recovery time under normal temperature.

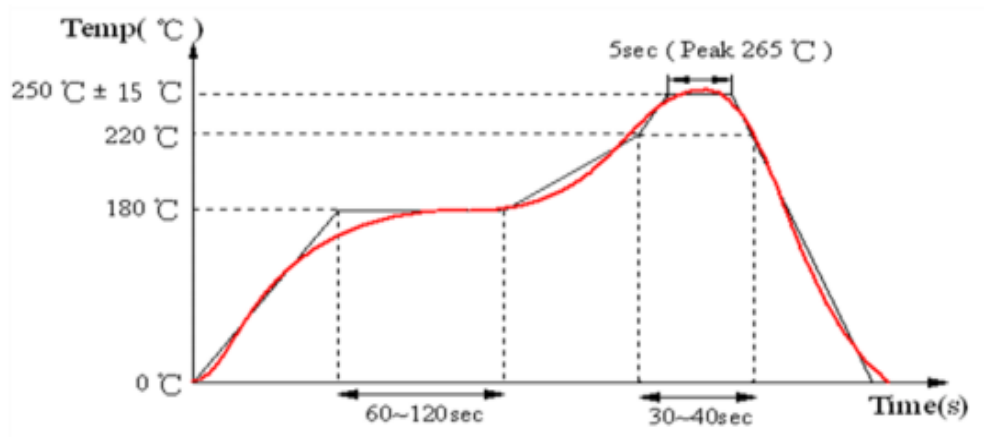
6.8. Low Temperature Endurance

The device should fulfil the electrical specification after being exposed to the temperature -40 °C ± 5 °C for 96 ± 2 hours and to 2 hours recovery time under normal temperature.

6.9. Temperature Cycle Test

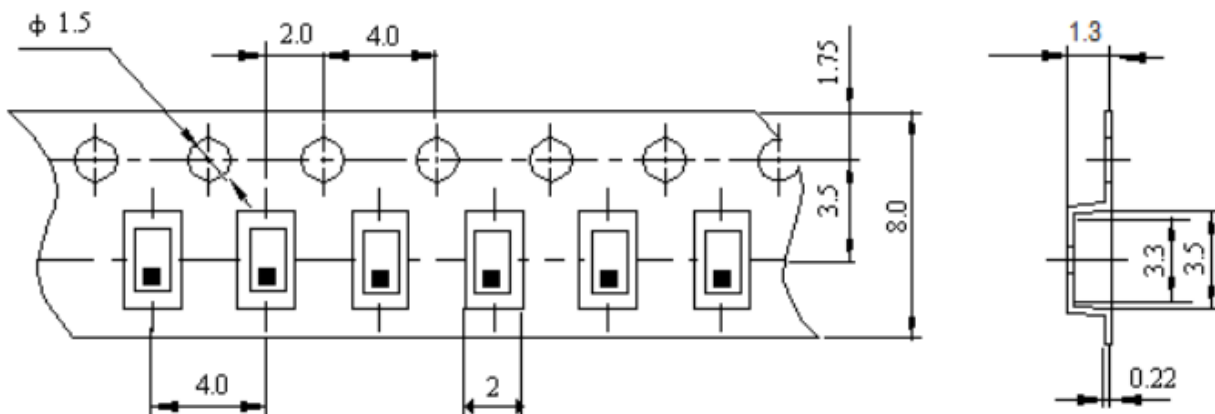
The device should fulfil the electrical specification after being exposed to the low temperature -40 °C and high temperature $+85$ °C for 30 ± 2 min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

7 Reflow Soldering Standard Condition



8 Packaging and Dimensions

8.1. Plastic Tape



Remarks for Package:

Reserve a length of 150–200 mm for the trailer of the carrier and 250–300 mm for the leader of the carrier and further 250 mm of cover tape at the leading part of the carrier.

8.2. Reel (3000 pcs/reel)

